





DUAL SURFACE MOUNT SWITCHING DIODE

Features

- · Fast Switching Speed
- Surface Mount Package Ideally Suited for Automated Insertion
- For General Purpose Switching Applications
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Notes 3 & 4)
- Qualified to AEC-Q101 Standards for High Reliability

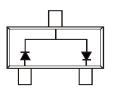
Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: See Diagram
- Weight: 0.008 grams (approximate)

SOT23



Top View



Top View Internal Schematic

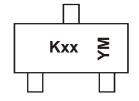
Ordering Information (Note 5)

| Part Number | Compliance | Case | Packaging |
|-------------|------------|-------|--------------------|
| BAV99-7-F | Standard | SOT23 | 3,000/Tape & Reel |
| BAV99-13-F | Standard | SOT23 | 10,000/Tape & Reel |
| BAV99Q-7-F | Automotive | SOT23 | 3,000/Tape & Reel |
| BAV99Q-13-F | Automotive | SOT23 | 10,000/Tape & Reel |

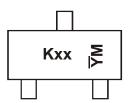
Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Product manufactured with Date Code 9W (week 39, 2009) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 9W are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



xx = JE, Product Type Marking Code YM = Date Code Marking for Shanghai Assembly / Test site Y = Year (ex: A = 2013) M = Month (ex: 9 = September)



xx = JE, Product Type Marking Code $\overline{Y}M = Date$ Code Marking for Chengdu Assembly / Test site

 \overline{Y} = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

| Year | 1998 | 1999 | | 2006 | 2007 | 2008 | 2009 | 2010 | 2011 | 2012 | 2013 | 2014 | 2015 | 2016 | 2017 |
|-------|------|------|-----|------|------|------|------|------|------|------|------|------|------|------|------|
| Code | J | K | | Т | U | V | W | Χ | Υ | Z | Α | В | C | D | Е |
| Month | Jan | Fe | b I | Mar | Apr | May | Ju | n | Jul | Aug | Sep | Oc | t N | Nov | Dec |
| Code | 1 | 2 | | 3 | 4 | 5 | 6 | | 7 | 8 | 9 | 0 | | N | D |



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | | Symbol | Value | Unit |
|--|---------------------------|--|------------|----------|
| Non-Repetitive Peak Reverse Voltage | | V_{RM} | 100 | V |
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | | V _{RRM} V _{RWM} VR | 75 | V |
| RMS Reverse Voltage | | V _{R(RMS)} | 53 | V |
| Forward Continuous Current (Note 6) | | I _{FM} | 300 | mA |
| Non-Repetitive Peak Forward Surge Current | @ t = 1.0µs @ t = 1.0s | I _{FSM} | 2.0 1.0 | Α |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|---|-----------------------------------|-------------|------|
| Power Dissipation (Note 6) | P _D | 350 | mW |
| Thermal Resistance Junction to Ambient Air (Note 6) | $R_{	heta JA}$ | 357 | °C/W |
| Operating and Storage Temperature Range | T _J , T _{STG} | -65 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

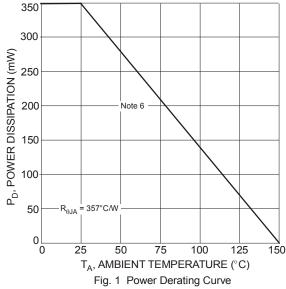
| Characteristic | Symbol | Min | Max | Unit | Test Condition |
|------------------------------------|--------------------|-----|-------------------------------|----------|--|
| Reverse Breakdown Voltage (Note 7) | V _{(BR)R} | 75 | _ | V | I _R = 2.5μA |
| Forward Voltage | V _F | _ | 0.715 0.855 1.0 1.25 | V | I _F = 1.0mA I _F = 10mA I _F = 50mA I _F = 150mA |
| Reverse Current (Note 7) | I _R | _ | 2.5 50 30 25 | μA μA | $V_R = 75V$ $V_R = 75V$, $T_J = +150^{\circ}C$ $V_R = 25V$, $T_J = +150^{\circ}C$ $V_R = 20V$ |
| Total Capacitance | C _T | _ | 2.0 | pF | V _R = 0, f = 1.0MHz |
| Reverse Recovery Time | t _{rr} | _ | 4.0 | ns | $I_F = I_R = 10 \text{mA},$ $I_{rr} = 0.1 \text{ x } I_R, R_L = 100 \Omega$ |

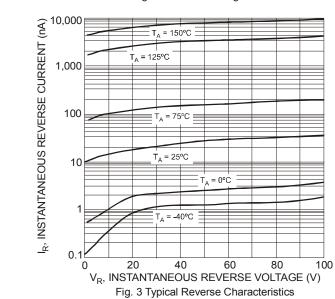
Notes:

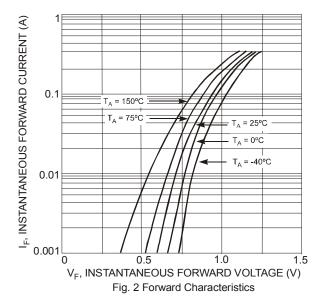
^{6.} Part mounted on Polymide PC board with pad dimensions 1.13mm x 1.27mm.

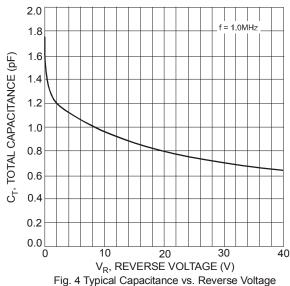
^{7.} Short duration pulse test used to minimize self-heating effect.





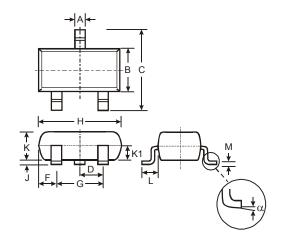






Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

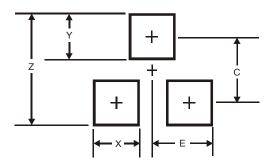


| SO123 | | | | | | | |
|----------------------|-----------|------|-------|--|--|--|--|
| Dim | Min | Max | Тур | | | | |
| Α | 0.37 | 0.51 | 0.40 | | | | |
| В | 1.20 | 1.40 | 1.30 | | | | |
| С | 2.30 | 2.50 | 2.40 | | | | |
| D | 0.89 | 1.03 | 0.915 | | | | |
| F | 0.45 | 0.60 | 0.535 | | | | |
| G | 1.78 | 2.05 | 1.83 | | | | |
| Н | 2.80 3.00 | | 2.90 | | | | |
| J | 0.013 | 0.10 | 0.05 | | | | |
| K | 0.903 | 1.10 | 1.00 | | | | |
| K1 | - | - | 0.400 | | | | |
| L | 0.45 | 0.61 | 0.55 | | | | |
| M | 0.085 | 0.18 | 0.11 | | | | |
| α | 0° | 8° | - | | | | |
| All Dimensions in mm | | | | | | | |



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | Value (in mm) | | |
|------------|---------------|--|--|
| Z | 2.9 | | |
| Х | 0.8 | | |
| Υ | 0.9 | | |
| С | 2.0 | | |
| E | 1.35 | | |

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